

Substitute for form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

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| Application Number | 09/825,648 |
| Filing Date | April 4, 2001 |
| First Named Inventor | Joseph Wytman |
| Art Unit | 1753 |
| Examiner Name | Brian L. Mutschler |
| Attorney Docket Number | 3481P009D |

U.S. PATENT DOCUMENTS

| Examiner Initials* | Cite No. ¹ | Document Number | Publication Date or Issue Date MM-DD-YYYY | Name of Patentee or Applicant of Cited Document | Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear |
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**Examiner
Signature**

Brian L Mutsaers

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| Date | |
| Considered | |

8/13/2003

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

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OTHER ART - NON PATENT LITERATURE DOCUMENTS

| Examiner Initials* | Cite No. ¹ | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. | T ² |
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| Examiner Signature | <i>Brian L Mutschler</i> | Date Considered | 8/13/2003 |
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